

Amendments to the Specification

Please amend paragraph [0024] as follows:

The present embodiment may decrease the total thermal resistance by providing one or more outlet vents **12** disposed on a portion of a surface of the case **11**, which could increase the potential for more natural convection as opposed to conduction through the case walls. In one embodiment a screen 31 may be placed over the vents **12** to obstruct contaminants from entering the interior portions of the case **11**.

Please amend paragraph [0025] as follows:

Fig. 3 illustrates an exploded view of a standardized peripheral device **13** with a thermal management arrangement including an inlet vent **28** and an outlet vent **32**, disposed in the same or different surfaces of the case **14**, in accordance with one embodiment of this invention. This embodiment may take advantage of external air currents to facilitate the heat transfer away from the integrated circuit **20**. In one embodiment a portion of the standardized peripheral device **13** may be placed entirely within an interior cavity of a host device. The host device may have another thermal management arrangement that results in air currents inside the interior cavity of the host device. In this embodiment the case **14** may be designed to take advantage of such an air current. Air from the ambient, which in this embodiment is the interior cavity of the host device, may be directed into the interior of the standardized peripheral device **13** by an inlet vent **28**. In one embodiment the inlet vent **28** may be designed with an upward

flange 33 (shown below in FIG. 4) to facilitate the intake of a laminar flow over the case 14.

Please amend paragraph [0026] as follows:

Fig. 4 illustrates a cross-sectional view of the standardized peripheral device **13** with a simplified pictorial representation of an air flow path through the interior of the device, in accordance with one embodiment of the present invention. The air flow may travel over the integrated circuit **20**, which may result in an overall increase in the heat transfer coefficient. As a result at least a portion of the thermal energy emitted from the integrated circuit **20** may be dissipated into and carried away by the current. Some of the heated air flow may then exit through the outlet vent **32** and thereby discharge a portion of the excess thermal energy back into the ambient. In one embodiment the outlet vent **32** may include a downward flange 35 to facilitate the exhaust of a laminar flow of heated air from the standardized peripheral device **13** into the ambient.